



RE434-LF

- Epoxy fibre-glass FR4 0.80 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Hot air leveling (HAL-leadfree)
- SMD hole spacing 1.25 x 1.25 mm
- 40 x 60 soldering pads 1.00 x 1.00 mm
- Hole diameter 0.35 mm
- Size 53 x 95 mm